COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: PMP10407

PCB VIEWED FROM TOP SIDE | BOARD #: PMP10407 | REV: B | SUN REV: Not In VersionControl
---|---|---|---
IGNORE -> | Top Overlay | | |

PLOT NAME = Top Assembly Drawing | GENERATED : 5/6/2015 12:13:24 AM | TEXAS INSTRUMENTS
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